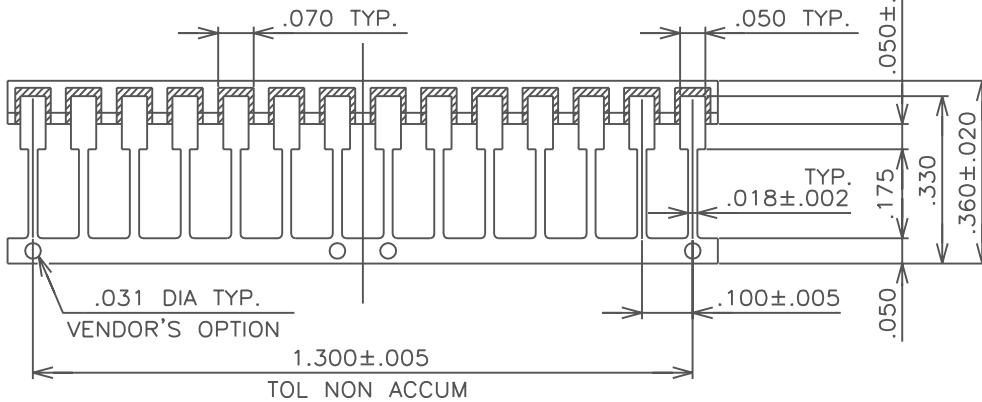


DETAIL-A

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. GND PADS TO BE ELECTRICALLY CONNECTED TO DIE ATTACH PAD.
6. LEAD RESISTANCE : 0.60 OHM MAX.



VENDOR'S OPTION

SB028W470-1				S=0 D=0
DRAWN	CHECKED	APPROVED	DATE	
S.S	K.K	M.K	JUN.20.'89	
DRAWING NO.				SHEET
KD-S89470-B				1/2

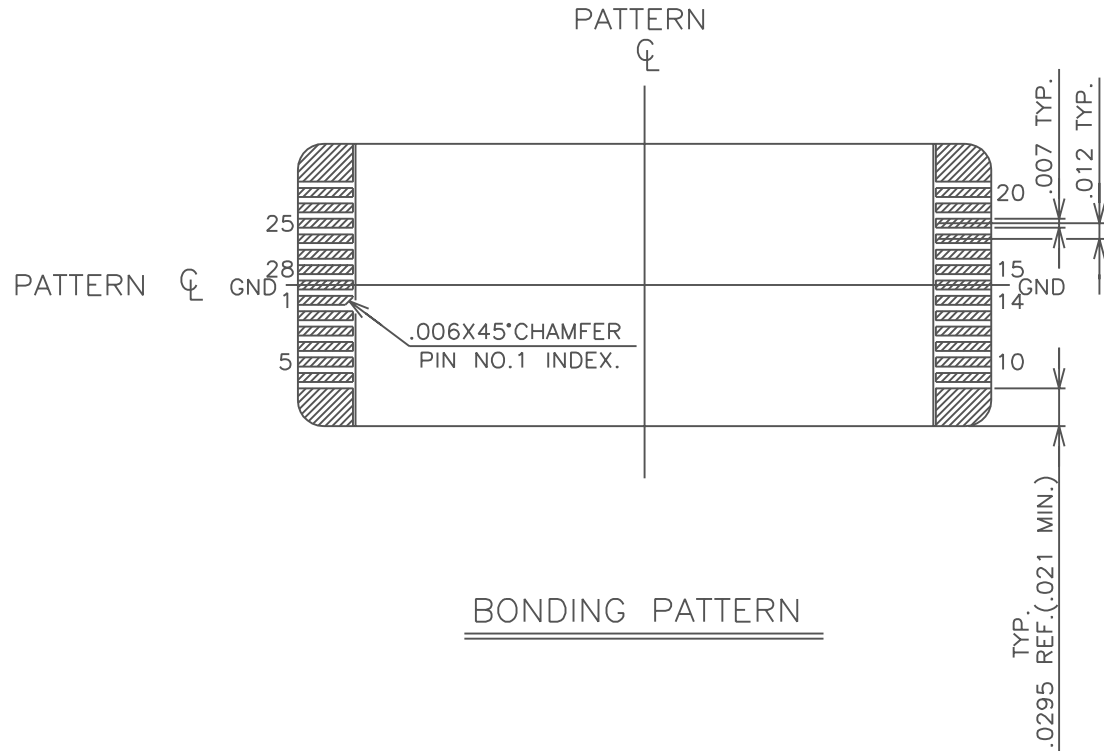
MODIFICATION

NAME	28 LEAD SIDE BRAZED PACKAGE			
SCALE	4 / 1	MATERIAL	AS INDICATED	
TOLERANCE	UNLESS OTHERWISE SPECIFIED			
	±.005			
	THIRD ANGLE PROJECTION			
REDRAWN ( CONVERTED CAD DATA )	OCT.18.'96	S.TH	H.S/K.I	T.A
CHANGED	DATE	DRAWN	CHECKED	APPROVED



KYOCERA CORPORATION  
KYOTO JAPAN





MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						28 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.S	K.K	M.K	JUN.20.'89
						SCALE 10/1	MATERIAL				
							THIRD ANGLE PROJECTION				
	REDRAWN	OCT.18.'96	S.T	H.S/K.I	T.A	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KD-S89470-B			2/2	

